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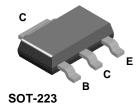
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## **TN6715A**

## **NZT6715**





## **NPN General Purpose Amplifier**

This device is designed for general purpose medium power amplifiers and switches requiring collector currents to 1.2 A. Sourced from Process 38.

## **Absolute Maximum Ratings\***

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	50	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
I <sub>C</sub>	Collector Current - Continuous	1.5	A
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### **Thermal Characteristics** TA = 25°C unless otherwise noted

Symbol	Characteristic	М	Units	
		TN6715A	*NZT6715	
P <sub>D</sub>	Total Device Dissipation	1.0	1.0	W
	Derate above 25°C	8.0	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	50		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	125	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm<sup>2</sup>.

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## **NPN General Purpose Amplifier**

(continued)

Electri	cal Characteristics TA = 25	°C unless otherwise noted			
Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHAF	RACTERISTICS				

$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage*	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$	40		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100  \mu A,  I_E = 0$	50		V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 100  \mu A,  I_C = 0$	5.0		V
I <sub>CBO</sub>	Collector-Cutoff Current	$V_{CB} = 50 \text{ V}, I_{E} = 0$		0.1	μΑ
I <sub>EBO</sub>	Emitter-Cutoff Current	$V_{EB} = 5.0 \text{ V}, I_{C} = 0$		0.1	μΑ

#### **ON CHARACTERISTICS**

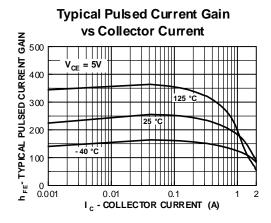
h <sub>FE</sub>	DC Current Gain	$I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	55		
		$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60		
		$I_C = 1.0 \text{ A}, V_{CE} = 1.0 \text{ V}$	50	250	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$		0.5	V
$V_{BE(on)}$	Base-Emitter On Voltage	$I_C = 1.0 \text{ A}, V_{CE} = 1.0 \text{ V}$		1.2	V

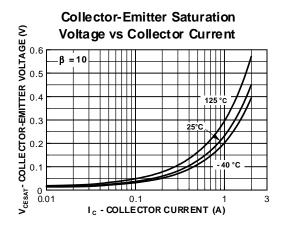
#### SMALL SIGNAL CHARACTERISTICS

h <sub>fe</sub>	Small-Signal Current Gain	$I_C = 50 \text{ mA}, V_{CE} = 10 \text{ V},$ f = 20  MHz	2.5	20	
C <sub>cb</sub>	Collector-Base Capacitance	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1.0 \text{ MHz}$		30	pF

<sup>\*</sup>Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 1.0%

## **Typical Characteristics**

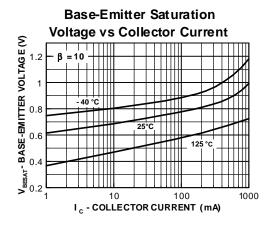


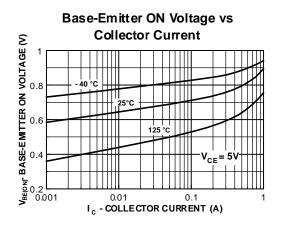


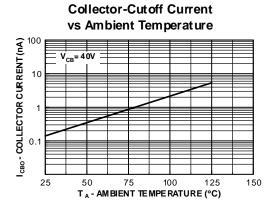
## **NPN General Purpose Amplifier**

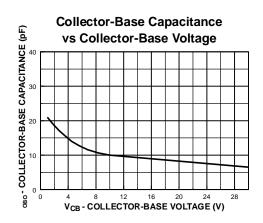
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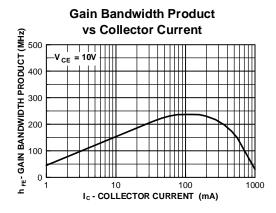
## Typical Characteristics (continued)

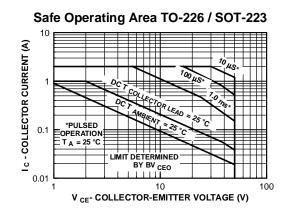








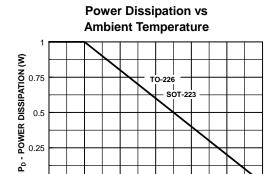




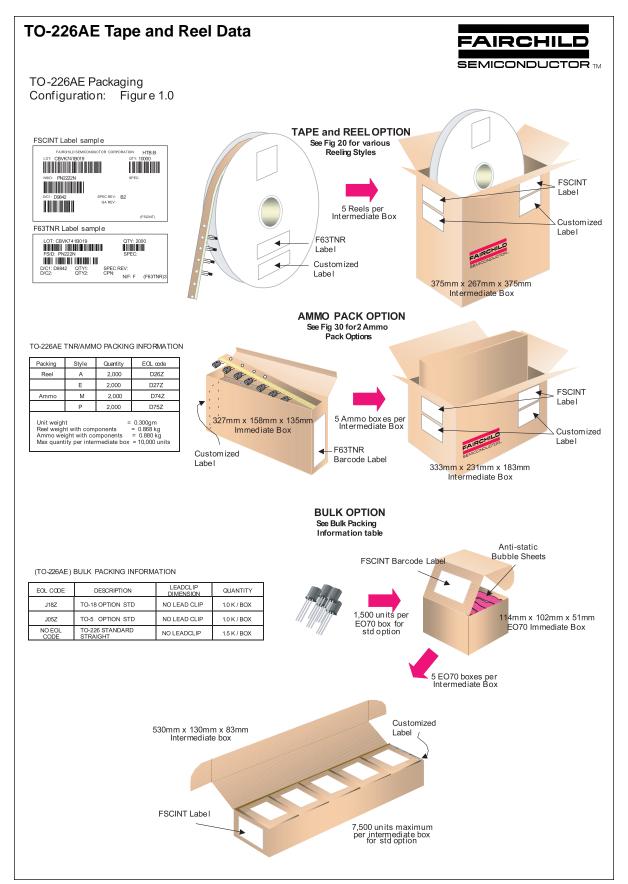
# NPN General Purpose Amplifier (continued)

## Typical Characteristics (continued)

0



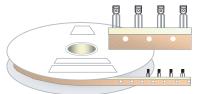
50 75 100 TEMPERATURE (°C)



## **TO-226AE Tape and Reel Data, continued**

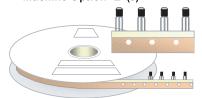
**TO-226AE Reeling Style Configuration:** Figure 2.0

#### Machine Option "A" (H)



Style "A" D26Z, D70Z (s/h)

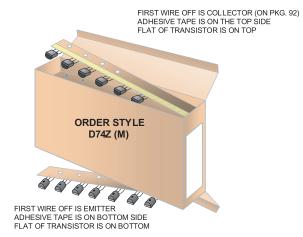
#### Machine Option "E"(J)



Style "E" D27Z, D71Z (s/h)

## TO-226AE Radial Ammo Packaging

Configuration: Figure 3.0



FIRST WIRE OFF IS EMITTER (ON PKG. 92) ADHESIVE TAPE IS ON THE TOP SIDE FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

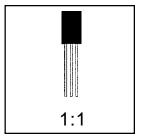
#### **TO-226AE Tape and Reel Data, continued** TO-226AE Tape and Reel Taping Dimension Configuration: Figure 4.0 ITEM DESCRIPTION SYMBOL DIMENSION Base of Package to Lead Bend 0.098 (max) Component Height Hb 1.078 (+/- 0.050) User Direction of Feed 0.630 (+/- 0.020) Lead Clinch Height HO Component Base Height H1 0.748 (+/- 0.020) Component Alignment (side/side) Pd 0.040 (max) 0.031 (max) Component Alignment ( front/back ) Hd 0.500 (+/- 0.020) Component Pitch РО Feed Hole Pitch 0.500 (+/- 0.008) Hole Center to First Lead P1 0.150 (+0.009, -0.010) Hole Center to Component Center P2 0.247 (+/- 0.007) Lead Spread F1/F2 0.104 (+/- 0 010) Lead Thickness d 0.018 (+0.002, -0.003) 0.429 (max) Cut Lead Length Taped Lead Length 0.209 (+0.051, -0.052) L1 Taped Lead Thickness 0.032 (+/- 0.006) Carrier Tape Thickness t1 0.021 (+/- 0.006) TO-226AE Reel Carrier Tape Width 0.708 (+0.020, -0.019) W Configuration: Figure 5.0 Hold - down Tape Width wo 0.236 (+/- 0.012) 0.035 (max) Hold - down Tape position W1 0.360 (+/- 0.025) W2 Feed Hole Position 0.157 (+0.008, -0.007) Sprocket Hole Diameter DO 0.004 (max) Lead Spring Out S Note: All dmensions are in inches. D4 ITEM DESCRIPTION SYMBOL MINIMUM MAXIMUM Red Diameter 13975 14025 Arbor Hole Diameter (Standard) 1.200 D2 1.160 D2 0.650 0.700 (Small Hole) Core Diameter D3 3.100 3.300 Hub Recess Inner Diameter D4 3.100 Hub Recess Depth W 1 0.370 0.570 Range to Range Inner Width W2 1.630 1.690 Hub to Hub Center Width 2.090 WЗ Note: All dimensions are inches

## **TO-226AE Package Dimensions**



# TO-226AE (FS PKG Code 95, 99)

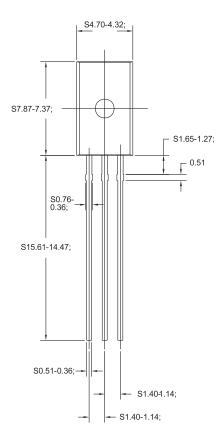


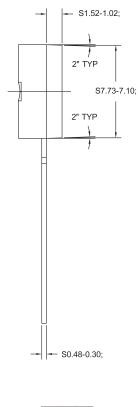


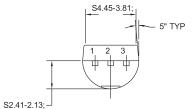
Scale 1:1 on letter size paper

Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.300







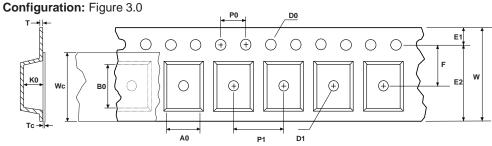
	PIN	99	95				
	1	Е	Е				
	2	В	С				
	3 C B						
TO-226AE (95,99)							

For leadformed option ordering, refer to Tape & Reel data information.

#### **SOT-223 Tape and Reel Data** FAIRCHILD SEMICONDUCTOR TM **SOT-223 Packaging** Configuration: Figure 1.0 Customized Label **Packaging Description:** Packaging Description: SOT-223 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate reason. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13° o 330cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 500 units per 7° or 177cm diameter reel. This and some other options are further described in the Packaging Information table. F63TNR Label Antistatic Cover Tape These full reles are individually barcode labeled and placed inside a standard intermediate box (flustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains two reels maximum. And these boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts Static Dissipative shipped. **Embossed Carrier Tape** Packaging Option no flow code **SOT-223 Unit Orientation** TNR Packaging type TNR Qty per Reel/Tube/Bag 2,500 500 Reel Size 13" Dia 7" Dia Box Dimension (mm) 343x64x343 184x187x47 Max qty per Box 5.000 1.000 343mm x 342mm x 64mm Weight per unit (gm) 0.1246 0.1246 F63TNR Label Intermediate box for Standard Weight per Reel (kg) 0.7250 0.1532 F63TNR Label F63TNR Label sample 184mm x 184mm x 47mm QTY: 3000 Pizza Box for D84Z Option **SOT-223 Tape Leader and Trailer** SPEC REV: CPN: D/C1: D9842 D/C2: Configuration: Figure 2.0 QTY1 QTY2 (F63TNR)3 $\bigcirc$ $\bigcirc$ 0 0 $\bigcirc$ $\circ$ 0 $\bigcirc$ 0 0 Components Trailer Tape Leader Tape 300mm minimum or 500mm minimum or 38 empty pockets 62 empty pockets



### **SOT-223 Embossed Carrier Tape**



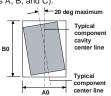


Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	Т	Wc	Тс
<b>SOT-223</b> (12mm)	6.83 +/-0.10	7.42 +/-0.10	12.0 +/-0.3	1.55 +/-0.05	1.50 +/-0.10	1.75 +/-0.10	10.25 min	5.50 +/-0.05	8.0 +/-0.1	4.0 +/-0.1	1.88 +/-0.10	0.292 +/- 0.0130	9.5 +/-0.025	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

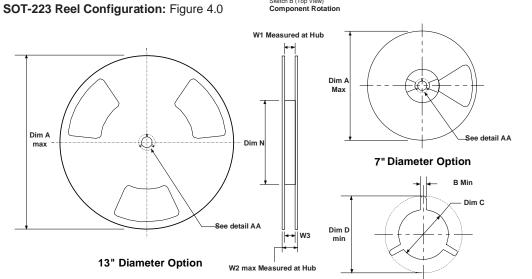


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

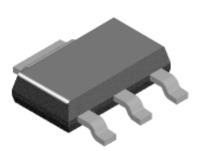
DETAIL AA

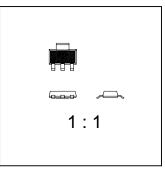


Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
12mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	5.906 150	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4
12mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	7.00 178	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4



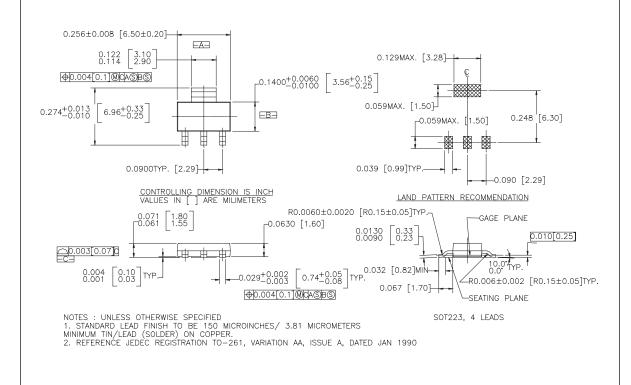
# SOT-223 (FS PKG Code 47)





Scale 1:1 on letter size paper

Part Weight per unit (gram): 0.1246



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